



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0805             |
| L         | 2mm +/-0.2mm     |
| W         | 1.25mm +/-0.2mm  |
| T         | 0.78mm +/-0.10mm |
| S         | 0.75mm MIN       |
| B         | 0.5mm +/-0.25mm  |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000                   |

### General Information

|                  |  |
|------------------|--|
| Series           | SMD Comm COG SnPb  |
| Style            | SMD Chip   |
| Description      | SMD, MLCC, Ultra-Stable, Low Loss, Class I   |
| Features         | Ultra-Stable, Low Loss, Class I  |
| RoHS             | No   |
| Prop 65          | <b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> . |
| SCIP Number      | 5549986b-60cf-4a2a-afbb-4ad1d7a11dcb   |
| Termination      | Lead (SnPb)  |
| Marking          | No   |
| AEC-Q200         | No   |
| Component Weight | 11 mg  |
| Shelf Life       | 78 Weeks   |
| MSL              | 1  |

### Specifications

|  |                           |
|--|---------------------------|
| Capacitance  | 43 pF                     |
| Measurement Condition  | 1MHz 1.0Vrms              |
| Capacitance Tolerance  | 1%                        |
| Voltage DC   | 50 VDC                    |
| Dielectric Withstanding Voltage                                    | 125 VDC                   |
| Temperature Range  | -55/+125°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1MHz 1.0Vrms         |
| Aging Rate   | 0% Loss/Decade Hour       |
| Insulation Resistance  | 100 GOhms                 |